DECLARATION FOR PATENT APPLICATION AND APPOINTMENT OF ATTORNEY

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name; I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention (Design, if applicable) entitled:

INTEGRATED CIRCUIT PACKAGING FOR IMPROVING EFFECTIVE CHIP-BONDING AREA

he specification of which (check one): is attached hereto;	or was	filed on:	Audionion Number				
mendment(s) referred to above. I ac	nded on: have reviewed and cknowledge the du- ign priority benefits	understand the contents	nternational Application Number; s of the above-identified specification, including the claims ion which is material to patentability as defined in <i>Title</i> States Code §119 of any foreign application(s) for patent of inventor's certificate having a filing date before that of the	7, Coae of r inventor's co	reaerai ertificate		
HUILY IS CHANGE.	PRIC	OR FOREIGN APPLICA	ATION(S)		PRIORITY CLAIMED		
Number		Country	Day/Month/Year Filed	Yes	No		
091135243	REPUBLIC OF CHINA		29/11/2002	×			
		:					
	☐ Addition	al Priority Application	n(s) Listed on Following Page(s)				
I HEREBY CLAIM THE BEN	EFIT UNDER TIT	LE 35 U.S. CODE § 11	9(E) OF ANY U.S. PROVISIONAL APPLICATIONS LIS	TED BELOV	N.		
A	application Number		Day/Month/Year Filed				
			ation(s) Listed on Following Page(s)				
material to patentability as defined in <i>Title 37</i> , <i>Code of Federal Regulations</i> , § the national or PCT international filing date of this application: Application Number Filing Date			Status - Patented, Pending or Abandoned				
		ı					
					-		
be true; and further that these statemer or both, under Section 1001 of Title 18 issued thereon.	atements made here nts were made with 8 of the United State	in of my own knowledg the knowledge that will tes Code and that such w	plication(s) listed on Following Page(s) ge are true and that all statements made on information and ful false statements and the like so made are punishable by villful false statements may jeopardize the validity of the ap	y fine or improphication or a	any pater		
POWER OF ATTORNEY and transact all business in the Patent	and Trademark Offi	ice connected therewith:		osecute this a	pplicatio		
		•	Reg. No. 26,592	-			
I (we) authorize my (our) a regarding any matter related to the pro thereon, and any patent resulting there	eparation, examinat	tion, grant and maintena	from ChipMOS Technologies (Bermuda) Ltd. ChipMOS Tence of this application, any continuation, continuation-in-indraw this authorization in writing.	ECHNOLOG part or division	HES INC mal base		
SEND CORRESPONDENCE TO:	5205 LEESE	LAW OFFICE PLLC BURG PIKE, SUITE 14 URCH, VA. 22041	TELEPHONE CALLS TO: BRUCE H. TROXELL (703) 575-2711				
FULL NAME OF FIRST OR SOLE INVENTO	R Chung-Hung Lin	n ;	CITIZENSHIP Republic Of China				
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DATE >003/11/0	6	1	Signature Chung-Hung Lin.				

ATTORNEY/DOCKET No:

CONTINUATION OF DECLARATION FOR PATENT APPLICATION AND APPOINTMENT OF ATTORNEY

Page _ 2__

PRIOR FOREIGN APPLICATION(S)						PRIORITY CLAIMED		
Number		Country		Day/Month/Year Filed	Yes	No		
								
	PRIOR PR	ROVISIONAL APPLICA	TIONS 35 U.S	S. CODE § 119(E)				
Application Number		Filing Date		Status - Patented, Pending or Abandoned				

PRIO	R U.S. OR F	CT INTERNATIONAL	APPLICATIO	NS (35 U.S. CODE § 120)				
Application Number		Filing Date	Status - Patented, Pending or Abandone		loned			
		:						
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Date >03 /1/17			Signature Posse Howard					
			1	y distribution of the second		-		
Full Name of Joint Inventor			Citizenship Republic Of China					
Residence Address			Post Office Address Is the Same as Residence Address Unless Otherwise Shown below					
Date			Signature					

 $[\]hfill \square$ See following pages for additional joint inventors/priority applications.